

EMSG-701

导热硅脂

产品特征

随着电子元器件的微型化，放热器件需要有很好的导热介质使产生的热量有效地分解到环境中，从而避免电子元件过热而造成产品性能和寿命的问题。**EMSG-701**是应用于电子器件组装中的导热硅脂。它良好的导热性和优异的界面接触可以使热传导通畅。同时，**EMSG-701**具有低油离和适宜的流变性，即保障产品长期的导热效果又方便使用。

产品性能概况

| | EMSG-701 |
|----------------------------|--------------------|
| 颜色 | 白色 |
| 表象 | 膏状 |
| 组分 | 单组分 |
| 粘度, (mPa.s @ 25°C) | 不流淌 |
| 密度, (g/ml @ 25°C) | 2.12 |
| 热导率, (W/mK) | 1.0 |
| 最大颗粒, (micron) | 25 |
| 挥发成分, (%) | <1 |
| 油离度, 120°C for 24 hrs. (%) | <0.1 |
| 体积电阻率, (ohm.cm) | 1X10 ¹⁶ |
| 老化, 150°C for 24 hrs | 无变化 |
| 环保测试 RoHS | 通过 |

The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assure legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein. No warranty of fitness for a particular purpose is made. Properties are typical and not to be used as specifications.

使用说明

1. 所有的基材表面必须干净和干燥。
2. 将膏状硅脂涂在电子器件或散热器的平面上。
3. 将电子器件与散热器的平面压紧，使导热硅脂在两个平面之间形成非常薄的界面。
4. 加强散热器。

注意事项

- A. 导热硅脂接触的电子器件和散热器的平面要尽量平整。
- B. 如果硅脂在容器内有表面浮油，可以通过搅动把油混入硅脂中。
- C. 尽量避免气泡夹杂于硅脂中。
- D. 加固散热器的力度要适当平衡，以确保导热硅脂界面厚度均匀。

储存与产品保质期

EMSG-701 可以在室温下存储 24 个月。

安全

请参考本产品的材料安全数据表。

The information and statements herein are believed to be reliable but are not to be construed as a warranty or representation for which we assure legal responsibility. Users should undertake sufficient verification and testing to determine the suitability for their own particular purpose of any information or products referred to herein. No warranty of fitness for a particular purpose is made. Properties are typical and not to be used as specifications.